

ABSTRACT

A method for manufacturing an electronic device includes at least a step (1) of preparing a structure (100) comprising (i) an adhesive film (50) provided with a base material layer (10), an adhesive resin layer (A) provided on a first surface (10A) side of the base material layer (10), and an adhesive resin layer (B) provided on a second surface (10B) side of the base material layer (10) and in which an adhesive force is reduced by an external stimulus, in which a storage modulus E' at 125°C of the adhesive resin layer (A) is 0.2×10^6 Pa or more and 4.5×10^6 Pa or less, (ii) an electronic component (70) attached to the adhesive resin layer (A) of the adhesive film (50), and (iii) a support substrate (80) attached to the adhesive resin layer (B) of the adhesive film (50); a step (2) of sealing the electronic component (70) with a sealing material (60); a step (3) of peeling the support substrate (80) from the structure (100) by reducing an adhesive force of the adhesive resin layer (B) by applying an external stimulus; and a step (4) of peeling the adhesive film (50) from the electronic component (70).